

WUSB3801

USB Type-C Configuration Channel Flippable Adapter

http//:www.willsemi.com

Description

The WUSB3801 is a Type-C Configuration Channel (CC) Flippable Adapter chip with low power and high efficiency. The WUSB3801 supports channel identification of USB Type-C connector and auto detection of different power roles based on chip settings. This chip is compatible with USB Type-C Cable and Connector Specification Release 1.2 for varies of applications.

The WUSB3801 supports PIN control mode and I²C control mode through CTRL pin settings, and re-uses SDA (INOUT1)/SCL (INOUT2)/INTB (OUT3) pins to realize necessary functions in different control modes. ROLE pin is used for Source (SRC)/Sink (SNK)/Dual Role Power (DRP) mode selection of Type-C logic working state. The global enable signal comes from ENB pin with internal pull-up resistor for more feasibility.

Applications

- Smart-phones
- Laptops
- Tablets

Features

- USB Type-C Cable and Connector
 Specification Release 1.2 compatible
- Global power saving and active mode
- Pin or I²C controllable
- Support auto CC ports configuration
- Support SRC/SNK/DRP power mode
- Support DRP with Try.SNK or Try.SRC
- Support different current model controls and identifications (Default, 1.5A and 3.0A)
- Accurate internal CC termination resistance
 and current source with high precision
- High voltage EOS protection and DC 25V tolerance on CC1, CC2 and VBUSD pins
- Wide single power supply range: 2.7 ~ 5.5V
- QFN1616-12L packaging available (1.6x1.6x0.35mm)

Order Information

Device	Package	Shipping		
WUSB3801Q-12/TR	QFN1616-12L	3000/Reel&Tape		

Will Semiconductor Ltd. 1 Jul, 2016 - Rev. 1.1



Revision History

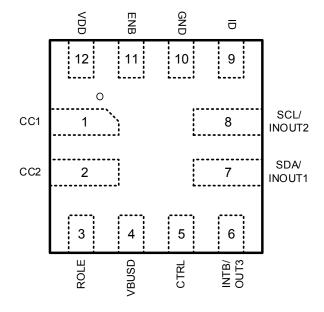
Version	Date	Owner	Description
0.0	2015-03	Y. Shen	Initial draft
0.1	2015-03	Y. Shen	Support high voltage mode and ENB as global reset
0.2	2015-04	Y. Shen	Type-C 1.1 compatible
0.3	2015-08	Y. Shen	Update I _{host} from 110μA to 122.5μA. Update I _{device} from 28μA to 22.5μA
0.4	2015-10	Y. Shen	Support DRP with Try.SNK or Try.SRC
0.5	2015-11	Y. Shen	WUSB3801QB marking change from B* to G*
0.6	2015-11	Y. Shen	Add recommend land pattern
1.0	2016-05	X. Chen	Type-C 1.2 compatible Add general marking M Use a clear function description for ID pin Update high voltage DC from 20V to 25V Update ESD HBM from 3500V to ± 4000 V Update ESD CDM from 1500V to ± 1500 V Update USB Max tri-state input threshold from VDD-0.5 to 2.9V Update VH and VL for logic threshold voltage from 0.8^* VDD to 1.05V and from 0.2^* VDD to 0.4 V Update Vth_BUS from 0.78^* VDD to 3.2V Update Inost max from 140µA to 160µA Correct figures for threshold of Comparison and Status Relationship Update all state diagrams based on chip functions Refine all descriptions and diagrams Remove repetitious descriptions as those in USB Type-C Specification

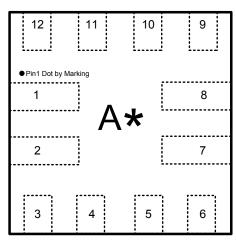
Will Semiconductor Ltd. 2 Jul, 2016 - Rev. 1.1



Pin Configuration (Top View)

Marking Information

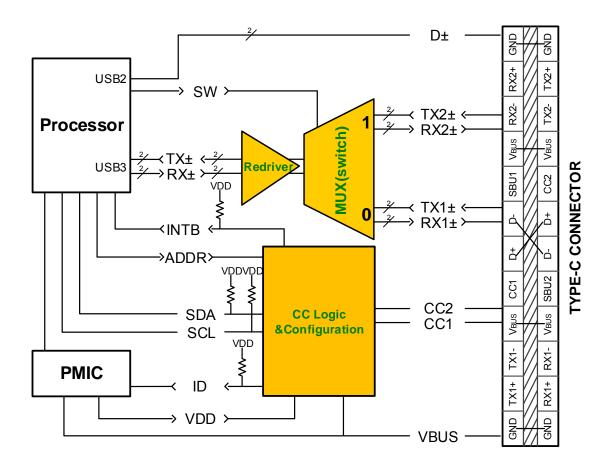




A = Device Code

★ = Month Code (A~Z)

Application Block Diagram





Pin Descriptions

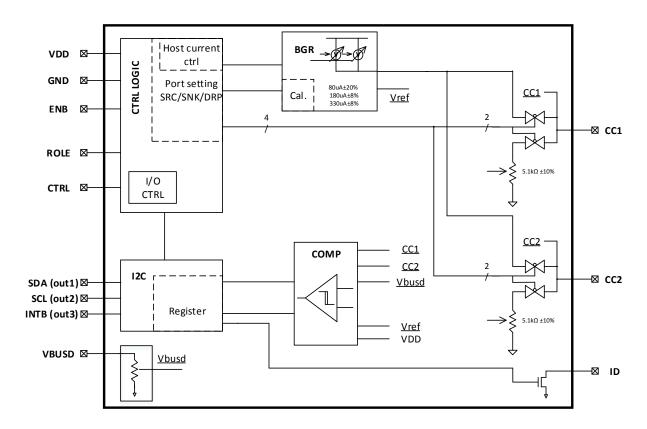
Table 1. Pin Descriptions

Pin	Name	Type	Function	Comments
1	CC1	I/O	Type-C CC logic channel signal High voltage EOS protection	Start from SNK when power on
2	CC2	I/O	Type-C CC logic channel signal High voltage EOS protection	Start from SNK when power on
3	ROLE	AI	Tri-state input control signal for working mode selection	Floating — DRP VDD — SRC GND — SNK
4	VBUSD	Al	V _{BUS} detection and high voltage protection: DC 25V AC lighting surge	Detect V _{BUS} voltage
5	CTRL	AI	Tri-state input control signal for PIN or I ² C control mode selection	Floating — PIN control mode VDD — I ² C control mode with control address 7b'1101000 GND — I ² C control mode with control address 7b'1100000
6	INTB/	DO	Interruption output signal for I ² C control mode	INTB output Low active
0	OUT3	DO	OUT3: Audio Acc. connection indification	H — No connectionL — Audio Acc. connected
7	SDA/ INOUT1	I/O	I ² C data input/output; INOUT1 and INOUT2 combined to identify the charging current mode when a SRC/SNK is connected	INOUT2 and INOUT1 in PIN control mode indifications 2b'11 – Default
8	SCL/ INOUT2	I/O	I ² C clock input; INOUT1 and INOUT2 combined to identify the charging current mode when a SRC/SNK is connected	2b'10 — 1.5A 2b'00 — 3.0A 2b'01 — No connection
9	ID	AO	Open drain output signal for SRC or DRP operating as SRC	Output Low when detects CC channel is connected as SRC or DRP operating as SRC
10	GND	G	Global ground	_
11	ENB	Al	Global enable signal	H — Power saving L — Active
12	VDD	Р	Power	2.7 ~ 5.5V

Will Semiconductor Ltd. 4 Jul, 2016 - Rev. 1.1



Block Diagram



Will Semiconductor Ltd. 5 Jul, 2016 - Rev. 1.1



Absolute Maximum Ratings

Table 2. Absolute Maximum Ratings

Symbol	Description	Range	Unit
V _{BUSD}	V _{BUS} pin voltage	-0.3 ~ 25	V
V _{CCx}	CC pin voltage	-0.3 ~ 25	V
V_{DD}	Power supply	-0.3 ~ 6.0	V
V _{IO}	Input IO voltage	-0.3 ~ 3.6	V
T _{sto}	Storage temperature	-65 ~ 150	°C
V _{НВМ}	ESD HBM	±4000	V
V _{CDM}	ESD CDM	±1500	V

The range is for stress ratings only. Stress exceeding the range specified in the Absolute Maximum Ratings may cause substantial damage to the device. Prolonged exposure to extreme conditions within the range may also affect device reliability.

Recommended Operation Conditions

Table 3. Recommended Operation Conditions

Symbol	Description	Test Condition	Min.	Тур.	Max.	Unit
V_{DD}	Power supply	-	2.7	-	5.5	V
V _{EN_L}	ENB pin Low voltage level	V _{DD} =3.6V	-	-	0.4	V
V _{EN_H}	ENB pin High voltage level	V _{DD} =3.6V	1.15	-	-	V
V _{ID_L} / V _{INTB_L}	ID/INTB pin Low voltage level Open drain output	V _{DD} =3.6V I _{Sink} = -2mA	-	-	0.4	V
V _{IO3_th}	USB tri-state input threshold	V _{DD} =3.6V	0.7	-	2.9	V
Tj	Junction temperature	-	-40	-	125	°C

Will Semiconductor Ltd. 6 Jul, 2016 - Rev. 1.1



Electronics Characteristics (V_{DD}=3.6V, T_a=25°C, unless otherwise noted)

Table 4. Electrical Characteristics

Parameters	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
		ENB=Low CC pins unattached	-	22.5	45	μΑ
Active current	I _{DD_active}	ENB=Low In Attached.SRC state Default current mode	-	122.5	160	μΑ
Power saving current	I _{DD_disab}	ENB=High	-	-	1	μΑ
Logic threshold	V _H	V _{DD} =3.6V	1.05	-	-	V
voltage	VL	V _{DD} =3.6V	-	-	0.4	V
	I _H	3.0A mode setting	304	330	356	μA
Current source	I _M	1.5A mode setting	166	180	194	μA
	I _D	Default mode setting	64	80	96	μΑ
Resistor load	R _d	-	4.6	5.1	5.6	kΩ
Comparator	V_{th_H}	3.0A mode setting	1.16	1.23	1.31	V
Comparator	V _{th_M}	1.5A mode setting	0.61	0.66	0.70	V
threshold voltage	V _{th_D}	Default mode setting	0.15	0.2	0.25	V
V _{BUS} detection threshold voltage	V _{th_BUS}	V _{DD} =3.6V	2.9	3.2	3.5	V

Will Semiconductor Ltd. 7 Jul, 2016 - Rev. 1.1



Function Descriptions

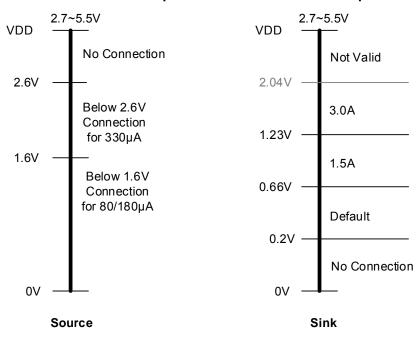
General Description

The WUSB3801 is a Type-C Configuration Channel Flippable Adapter chip with low power and high efficiency. The WUSB3801 supports channel identification of USB Type-C connector and auto detection of different power roles based on chip settings. It has high voltage protection circuits on CC1/CC2/VBUSD pins and supports both DC up to 25V and AC lighting surge. This chip is compatible with USB Type-C Cable and Connector Specification Release 1.2 for varies of applications.

Logic Control Block

The logic control block receives the outer control signals, detects CC connection status using voltage level comparisons of CC pins for different connection topologies and settings, and outputs the detected information of communication path. Comparison results showing CC signals voltage range are sent to logic control block for state machine and then the connection status of related working mode will be identified. When connection status changes, the logic control block will update outputs of pins and registers. The figures as below show the boundaries of status.

Threshold of Comparison and Status Relationship



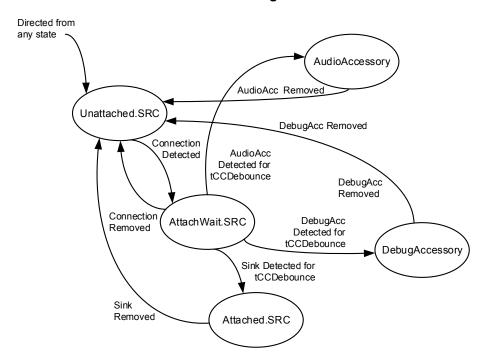
Will Semiconductor Ltd. 8 Jul, 2016 - Rev. 1.1



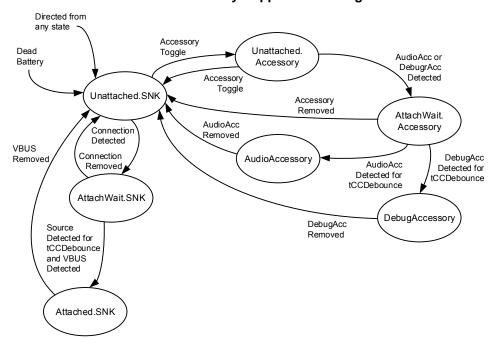
Work Mode Feature

According to CC connection status and detection results, the chip can work as SRC (Host), SNK (Device) or DRP mode which are shown in the following figures.

SRC State Diagram



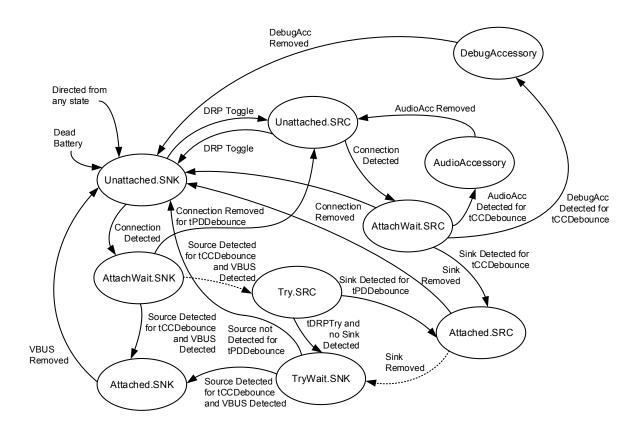
SNK with Accessory Support State Diagram



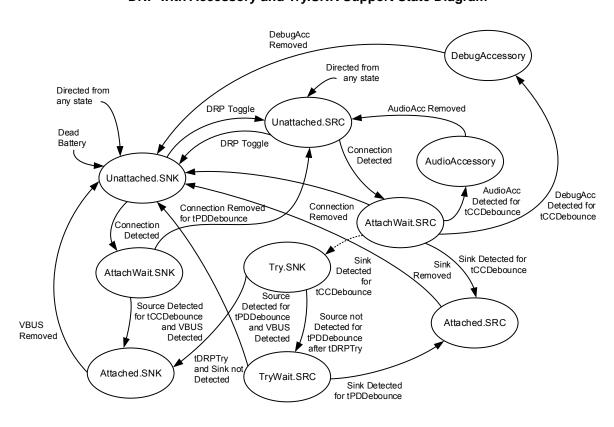
Will Semiconductor Ltd. 9 Jul, 2016 - Rev. 1.1



DRP with Accessory and Try.SRC Support State Diagram



DRP with Accessory and Try.SNK Support State Diagram



Will Semiconductor Ltd. 10 Jul, 2016 - Rev. 1.1



Communication Interfaces

I²C Interface

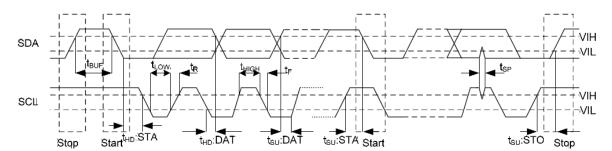
The chip can take communications over I²C bus which supports up to 400 kHz clock when CTRL pin is not floating (connected to VDD or GND). Two setting values would result in different I²C device addresses as shown in Table 7.

Table 7. Address Table Controlled by CTRL Pin

	Pin Setting	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1
Address 1	VDD	1	1	0	1	0	0	0
Address 2	GND	1	1	0	0	0	0	0

I²C Bus Timing

I²C BUS Timing Diagram



Will Semiconductor Ltd. 11 Jul, 2016 - Rev. 1.1



Electrical Characteristics of I²C

Table 8. Electrical Characteristics of I²C

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
f _{SCL}	SCL clock frequency	-	-	-	400	kHz
V _{DD_I2C}	Power supply range for I ² C	-	1.65	-	3.6	V
V _{IH}	Logic high level voltage (Note 1)	-	1.2	-		V
V _{IL}	Logic low level voltage (Note 1)	-	-	-	0.4	V
I _{sink}	Sink current at low level (open drain) (Note 1)	-	-	1.6	-	mA
t _{BUF}	Bus free time between a STOP and START condition	-	1.3	-	-	μs
t _{HD_STA}	Hold time START condition. After this period, the first clock pulse is generated	-	0.6	-	-	μs
t _{LOW}	LOW period of the SCL clock	-	1.3	-	-	μs
t _{HIGH}	HIGH period of the SCL clock	-	0.6	-	-	μs
tsu_sta	Set-up time for a repeated START condition	-	0.6	-	-	μs
t _{HD_DAT}	Data hold time between SDA and SCL falling edge	-	0	-	-	μs
t _{SU_DAT}	Data set-up time	-	100	-	-	ns
t _r	Rise time for SDA and SCL signals (Note 2)	-	-	-	300	ns
t _f	Fall time for SDA and SCL signals (Note 2)	-	1	-	300	ns
tsu_sto	Set-up time for STOP condition	-	0.6	-	-	μs
т.	Width of doglitch at input termination	SCL	-	200	-	ns
T _{deg}	Width of deglitch at input termination	SDA	-	250	-	ns
C _b	Capacitive load for each bus line	-	-	-	400	pF

Note 1: Guaranteed by design

Note 2: tr and tf are timing from 0.3*VDD to 0.7*VDD

Will Semiconductor Ltd. 12 Jul, 2016 - Rev. 1.1



I²C Register Map

Table 9. I²C Register Map

Addr.	Register	Туре	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0			
01H	Device ID	R		Version	ID: 000	10	10 \		/endor ID: 110				
			Acc. Support	Try SNK/SRC				Current Mode (SRC)		Work N	Mode Interruptio		
02H	Control	R/W	0: Yes 1: No 01: Try.SNK 10: Try.SRC 00/11: No Try		10: Try.SRC 01: 1.5A		00: SNK 01: SRC 10: DRP		1				
									Deta	ach/Attach			
03H	Interruption	R / Clear			Reser	ved			00: No Interruption01: Attached10: Detached				
			V _{BUS} Detection as SNK	Detection as		Current Plugged Port Status		t Status	Plug Orientation				
04H	CC Status	R	0: V _{BUS} not detected 1: V _{BUS} detected	SNK 00: Standby 01: Default 10: 1.5A 11: 3.0A		00: Standby 01: Default 10: 1.5A		00: Standby 01: Default 10: 1.5A		000: Standby 001: SNK 010: SRC 011: Audio Accessory 100: Debug Accessory		00: Standby 01: CC1 connected 10: CC2 connected 11: CC1 and CC2 connected	

Function Description

Registers are used for read/write settings in I2C control mode.

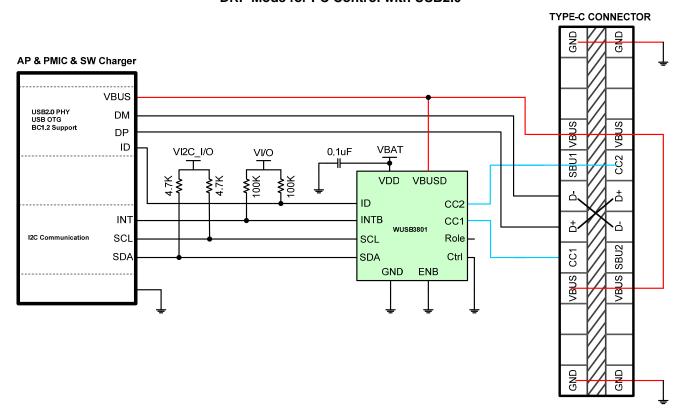
Status of USB Type-C connector is detected and updated in register map automatically by internal state machine. When any update occurs in register map after the last I2C reads, the chip would keep the interruption pin (INTB) at low level. Otherwise, the chip would cancel the interruption signal (INTB=1).

Will Semiconductor Ltd. 13 Jul, 2016 - Rev. 1.1

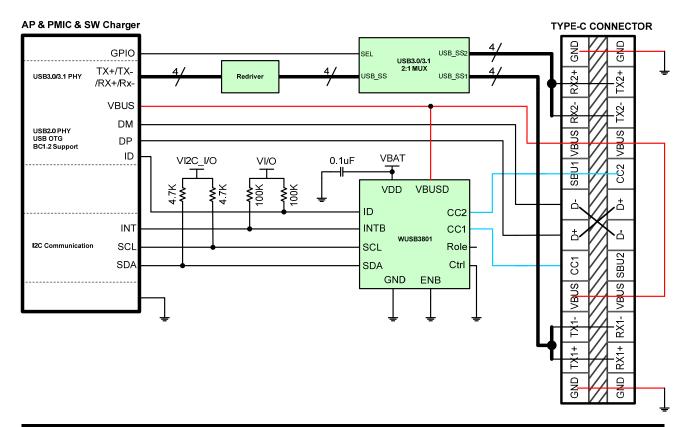


Typical Application Schematics

DRP Mode for I²C Control with USB2.0



DRP Mode for I²C Control with USB3.0/3.1

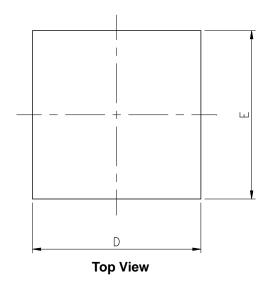


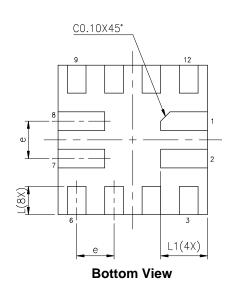
Will Semiconductor Ltd. 14 Jul, 2016 - Rev. 1.1



Package Outline Dimensions

QFN1616-12L





SEATING PLANE

SEATING PLANE

EVENT SEATING PLANE

SEATING PLANE

SEATING PLANE

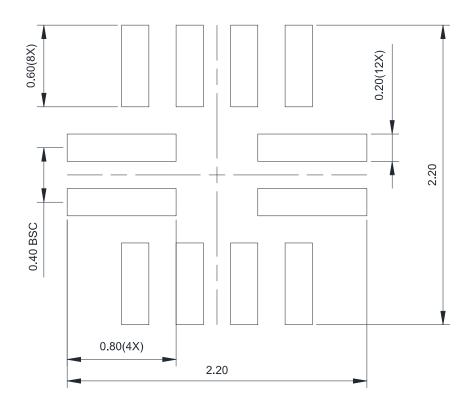
Description of the property o

Side View

Cumbal	Dimensions in millimeter						
Symbol	MIN.	NOM.	MAX.				
А	0.30	0.35	0.40				
A1	0.00	0.02	0.05				
A3	0.127 Ref.						
b	0.15	0.20	0.25				
D	1.55	1.60	1.65				
E	1.55	1.60	1.65				
е		0.40 BSC.					
L	0.25	0.30	0.35				
L1	0.45	0.50	0.55				



Recommend Land Pattern



RECOMMENDED LAND PATTERN

All dimensions are in millimeters